CLAIMS

1. A method for bonding a first substrate ~~(1a)~~ having a first surface ~~(2a)~~ to a second substrate ~~(1b)~~ having a second surface ~~(2b)~~, ~~characterized in that it comprises~~the method comprising the steps of:

- holding the first substrate ~~(1a)~~ by at least two support points ~~(S1, S2)~~,
- positioning the first substrate ~~(1a)~~ and the second substrate ~~(1b)~~ so that the first surface ~~(2a)~~ and the second surface ~~(2b)~~ face each other,
- deforming the first substrate ~~(1a)~~ by applying between at least one pressure point ~~(P1)~~ and the two support points ~~(S1, S2)~~, a strain ~~(F)~~ toward the second substrate ~~(1b)~~,
- bringing the deformed first surface ~~(2a)~~ and the second surface ~~(2b)~~ into contact,
- progressively releasing the strain ~~(F)~~,

wherein the surface area of the convex hull formed by the set of pressure points is null and the surface area of the convex hull formed by the set of support and pressure points is non-null.

~~2. A method according to claim 1, wherein the surface area of the convex hull formed by the set of pressure points is null and the surface area of the convex hull formed by the set of support and pressure points is non-null.~~

~~3~~2. A method according to ~~one of~~ claim~~s~~ 1 ~~to 2~~, wherein the first substrate ~~(1a)~~ is held by suckers ~~(3)~~ placed at the support points ~~(S1, S2)~~.

~~4~~3. A method according to claim ~~3~~2, wherein each sucker ~~(6)~~ is linked to a telescopic arm ~~(4)~~.

~~5~~4. A method according to ~~one of~~ claim~~s~~ 1 ~~to 2~~, wherein the second substrate ~~(1b)~~ is placed on a support ~~(10)~~ comprising at least two spacers ~~(11)~~ respectively on each sides of the second substrate ~~(1b)~~, said spacers being higher than the thickness of the second substrate ~~(1b)~~.

~~6~~5. A method according to claim ~~5~~4, wherein the first substrate ~~(~~1a~~)~~ is held by resting on the spacers ~~(~~11~~)~~, the support points ~~(~~S1, S2~~)~~ being points of contact between the spacers ~~(~~11~~)~~ and the first substrate.

~~7~~6. A method according to ~~one of~~ claim~~s~~ 4 or 5 ~~to 6~~, wherein the support ~~(~~10~~)~~ comprises at least one sucker ~~(~~12~~)~~ holding the second substrate ~~(~~1b~~)~~.

~~8~~7. A method according to one of claims 1 to ~~7~~6, wherein the strain ~~(~~F~~)~~ is applied by at least one piston rod ~~(~~5~~)~~.

~~9~~8. A method according to one of claims 1 to ~~8~~7, wherein the first substrate ~~(~~1a~~)~~ is a glass sheet, and wherein the second substrate ~~(~~1b~~)~~ is a silicon tile.

~~10~~9. A method according to one of claims 1 to ~~9~~8, wherein the first substrate ~~(~~1a~~)~~ is sequentially bonded to a plurality of second substrates ~~(~~1b~~)~~ by applying a strain ~~(~~F~~)~~ to the first substrate ~~(~~1a~~)~~ per second substrate ~~(~~1b~~)~~.

~~11~~10. A method according to claim~~s~~ ~~8~~ 7 and ~~10~~9, wherein the at least one piston rod ~~(~~5~~)~~ is mounted on a mobile device ~~(~~6~~)~~ and sequentially applies each strain ~~(~~F~~)~~ to the first substrate ~~(~~1a~~)~~.

~~12~~11. A method according to one of claims 1 to ~~9~~8, wherein the first substrate ~~(~~1a~~)~~ is simultaneously bonded to a plurality of second substrates ~~(~~1b~~)~~ by deforming the whole first substrate ~~(~~1a~~)~~.